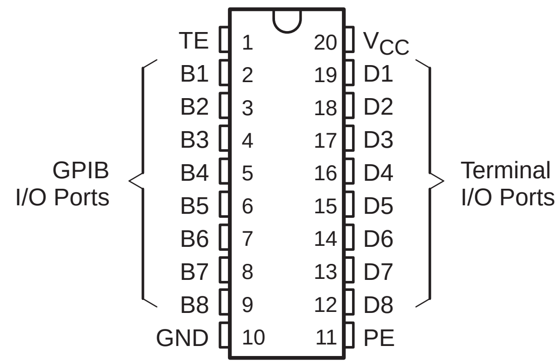
- **Suitable for IEEE Standard 488-1978 (GPIB)**
- **8-Channel Bidirectional Transceivers**
- **High-Speed Advanced Low-Power Schottky (ALS) Circuitry**
- **Low Power Dissipation . . . 46 mW Max Per Channel**
- **Fast Propagation Times . . . 20 ns Max**
- **High-Impedance pnp Inputs**
- **Receiver Hysteresis . . . 650 mV Typ**
- **Open-Collector Driver Output Option**
- **No Loading of Bus When Device Is Powered Down (V_{CC} = 0)**
- **Power-Up/Power-Down Protection (Glitch Free)**

DW OR N PACKAGE
(TOP VIEW)



description/ordering information

The SN75ALS160 eight-channel general-purpose interface bus transceivers are monolithic, high-speed, advanced low-power Schottky (ALS) devices designed for two-way data communications over single-ended transmission lines. This device is designed to meet the requirements of IEEE Standard 488-1978. The transceivers feature driver outputs that can be operated in either the passive-pullup or 3-state mode. If talk enable (TE) is high, these ports have the characteristics of passive-pullup outputs when pullup enable (PE) is low and of 3-state outputs when PE is high. Taking TE low places these ports in the high-impedance state. The driver outputs are designed to handle loads up to 48 mA of sink current.

An active turn-off feature has been incorporated into the bus-terminating resistors so that the device exhibits a high impedance to the bus when V_{CC} = 0. When combined with the SN75ALS161 or SN75ALS162 bus management transceiver, the pair provides the complete 16-wire interface for the IEEE-488 bus.

The SN75ALS160 is characterized for operation from 0°C to 70°C.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP (N)	Tube of 20	SN75ALS160N	SN75ALS160N
	SOIC (DW)	Tube of 25	SN75ALS160DW	75ALS160
		Reel of 2000	SN75ALS160DWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Function Tables

EACH DRIVER

INPUTS			OUTPUT
D	TE	PE	B
H	H	H	H
L	H	X	L
H	X	L	Z†
X	L	X	Z†

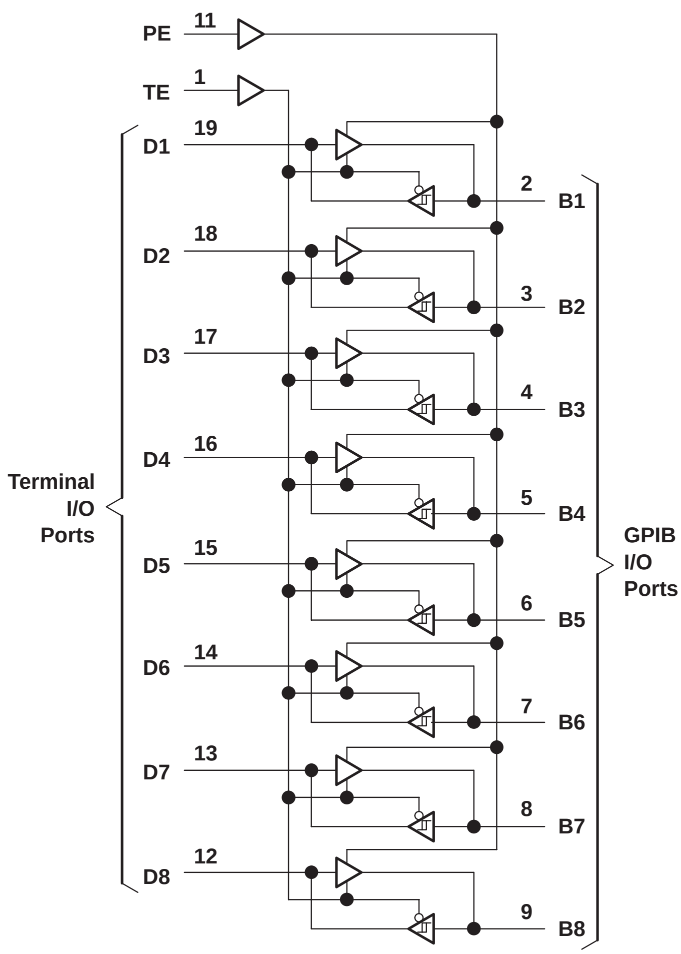
EACH RECEIVER

INPUTS			OUTPUT
B	TE	PE	D
L	L	X	L
H	L	X	H
X	H	X	Z

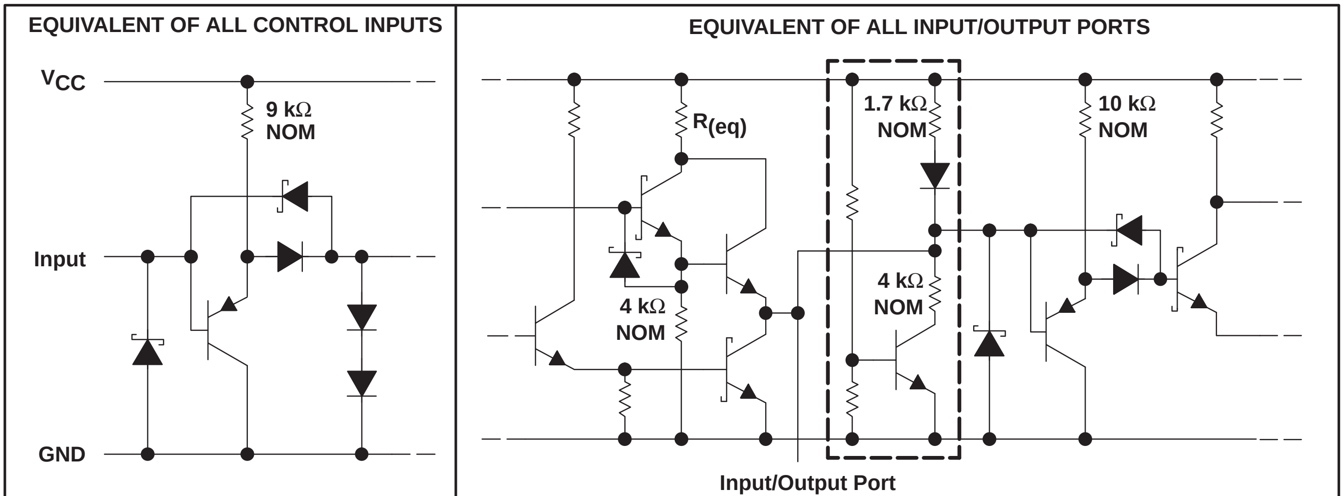
H = high level, L = low level, X = irrelevant, Z = high-impedance state

† This is the high-impedance state of a normal 3-state output modified by the internal resistors to V_{CC} and GND.

logic diagram (positive logic)



schematics of inputs and outputs



Driver output $R_{(eq)}$ = 30 Ω NOM
Receiver output $R_{(eq)}$ = 110 Ω NOM
$R_{(eq)}$ = equivalent resistor
Circuit inside dashed lines is on the driver outputs only.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1)		7 V
Input voltage, V_I		5.5 V
Low-level driver output current, I_{OL}		100 mA
Package thermal impedance, θ_{JA} (see Notes 2 and 3):	DW package	58°C/W
	N package	69°C/W
Operating virtual junction temperature, T_J		150°C
Storage temperature range, T_{stg}		−65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network ground terminal.
2. Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.75	5	5.25	V
V_{IH}	High-level input voltage		2			V
V_{IL}	Low-level input voltage				0.8	V
I_{OH}	High-level output current	Bus ports with pullups active			− 5.2	mA
		Terminal ports			− 800	µA
I_{OL}	Low-level output current	Bus ports			48	mA
		Terminal ports			16	
T_A	Operating free-air temperature		0		70	°C

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER			TEST CONDITIONS†			MIN	TYP‡	MAX	UNIT
V_{IK}	Input clamp voltage		$I_I = -18$ mA,	V_{CC} = MIN			− 0.8	− 1.5	V
V_{hys}	Hysteresis voltage ($V_{IT+} - V_{IT-}$)	Bus				0.4	0.65		V
V_{OH}§	High-level output voltage	Terminal	I_{OH} = − 800 µA,	TE at 0.8 V,	V_{CC} = MIN	2.7	3.5		V
		Bus	I_{OH} = − 5.2 mA,	PE and TE at 2 V,	V_{CC} = MIN	2.5	3.3		
V_{OL}	Low-level output voltage	Terminal	I_{OL} = 16 mA,	TE at 0.8 V,	V_{CC} = MIN		0.3	0.5	V
		Bus	I_{OL} = 48 mA,	TE at 2 V,	V_{CC} = MIN		0.35	0.5	
I_I	Input current at maximum input voltage	Terminal	V_I = 5.5 V,	V_{CC} = MAX			0.2	100	µA
I_{IH}	High-level input current	Terminal, PE, or TE	V_I = 2.7 V,	V_{CC} = MAX			0.1	20	µA
I_{IL}	Low-level input current	Terminal, PE, or TE	V_I = 0.5 V,	V_{CC} = MAX			−10	−100	µA
$V_{I/O(bus)}$	Voltage at bus port		$I_{I(bus)}$ = 0			2.5	3	3.7	V
			$I_{I(bus)}$ = −12 mA					−1.5	V
$I_{I/O(bus)}$	Current into bus port	Power on		$V_{I(bus)}$ = −1.5 V to 0.4 V		−1.3			mA
				$V_{I(bus)}$ = 0.4 V to 2.5 V		0		− 3.2	
				$V_{I(bus)}$ = 2.5 V to 3.7 V				2.5 − 3.2	
				$V_{I(bus)}$ = 3.7 V to 5 V		0		2.5	
				$V_{I(bus)}$ = 5 V to 5.5 V		0.7		2.5	
		Power off	V_{CC} = 0	$V_{I(bus)}$ = 0 to 2.5 V				40	µA
I_{OS}	Short-circuit output current	Terminal	V_{CC} = MAX			− 15	− 35	− 75	mA
		Bus	V_{CC} = MAX			− 25	− 50	− 125	
I_{CC}	Supply current		No load, V_{CC} = MAX	Terminal outputs low and enabled			42	65	mA
				Bus outputs low and enabled			52	80	
$C_{I/O(bus)}$	Bus-port capacitance		V_{CC} = 0 to 5 V,	$V_{I/O}$ = 0 to 2 V,	f = 1 MHz		30		pF

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ V_{OH} applies to 3-state outputs only.

switching characteristics at V_{CC} = 4.75 V, 5 V, and 5.25 V, T_A = 25°C (unless otherwise noted)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	Terminal	Bus	See Figure 1, C_L = 50 pF		10	17	ns
t_{PHL}	Propagation delay time, high- to low-level output					10	14	
t_{PLH}	Propagation delay time, low- to high-level output	Bus	Terminal	See Figure 2, C_L = 50 pF		8	15	ns
t_{PHL}	Propagation delay time, high- to low-level output					8	15	
t_{PZH}	Output enable time to high level	TE	Bus	See Figure 3, C_L = 50 pF		24	30	ns
t_{PHZ}	Output disable time from high level					9	14	
t_{PZL}	Output enable time to low level					16	28	
t_{PLZ}	Output disable time from low level					12	19	
t_{PZH}	Output enable time to high level	TE	Terminal	See Figure 4, C_L = 50 pF		24	36	ns
t_{PHZ}	Output disable time from high level					10	18	
t_{PZL}	Output enable time to low level					15	26	
t_{PLZ}	Output disable time from low level					15	24	
t_{en}	Output pullup enable time	PE	Bus	See Figure 5, C_L = 50 pF		16	24	ns
t_{dis}	Output pullup disable time					9	16	

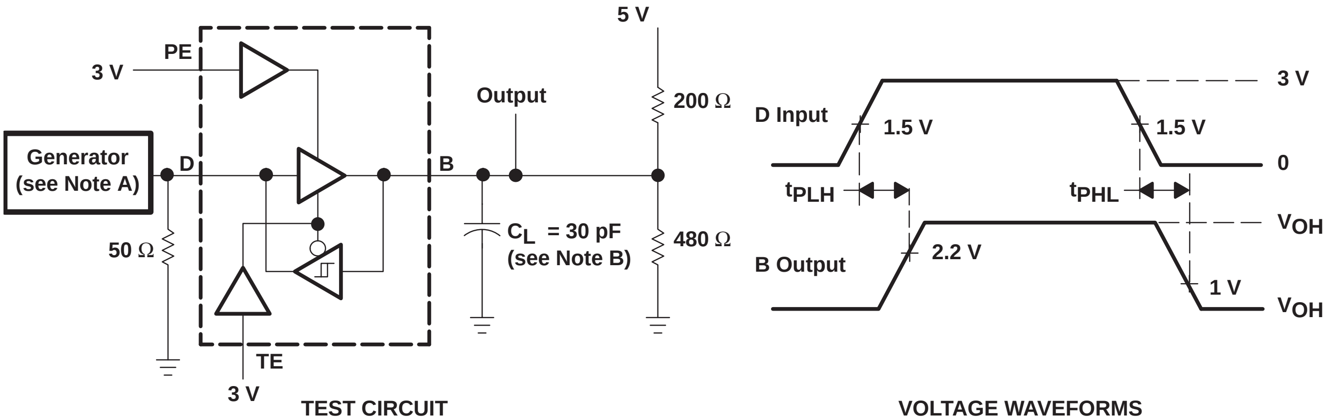
† All typical values are at V_{CC} = 5 V.

switching characteristics over recommended range of operating free-air temperature, V_{CC} = 5 V

PARAMETER		FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high-level output	Terminal	Bus	C_L = 30 pF, See Figure 1		7	20	ns
t_{PHL}	Propagation delay time, high- to low-level output					8	20	
t_{PLH}	Propagation delay time, low- to high-level output	Bus	Terminal	C_L = 30 pF, See Figure 2		7	14	ns
t_{PHL}	Propagation delay time, high- to low-level output					9	14	
t_{PZH}	Output enable time to high level	TE	Bus	C_L = 15 pF, See Figure 3		19	30	ns
t_{PHZ}	Output disable time from high level					5	12	
t_{PZL}	Output enable time to low level					16	35	
t_{PLZ}	Output disable time from low level					9	20	
t_{PZH}	Output enable time to high level	TE	Terminal	C_L = 15 pF, See Figure 4		13	30	ns
t_{PHZ}	Output disable time from high level					12	20	
t_{PZL}	Output enable time to low level					12	20	
t_{PLZ}	Output disable time from low level					11	20	
t_{en}	Output pullup enable time	PE	Bus	C_L = 15 pF, See Figure 5		11	22	ns
t_{dis}	Output pullup disable time					6	12	

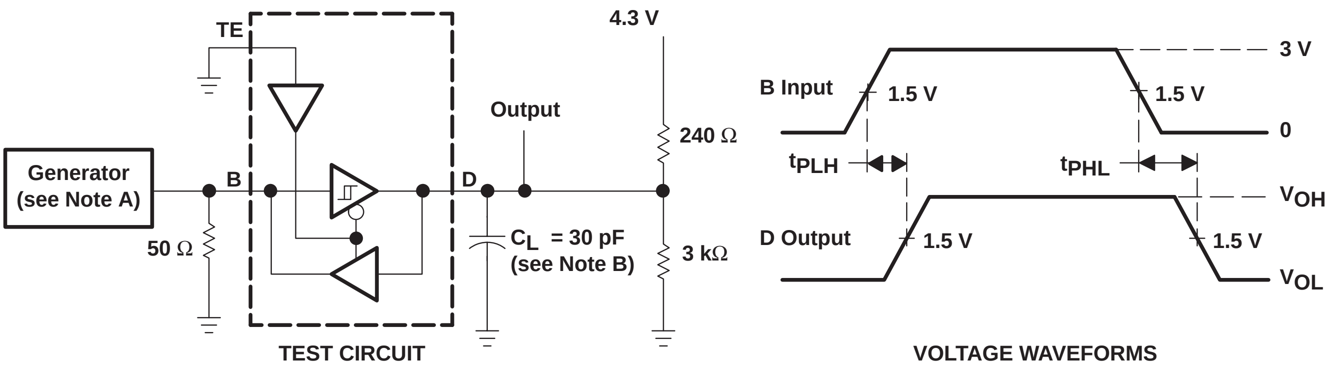
‡ Typical values are at T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

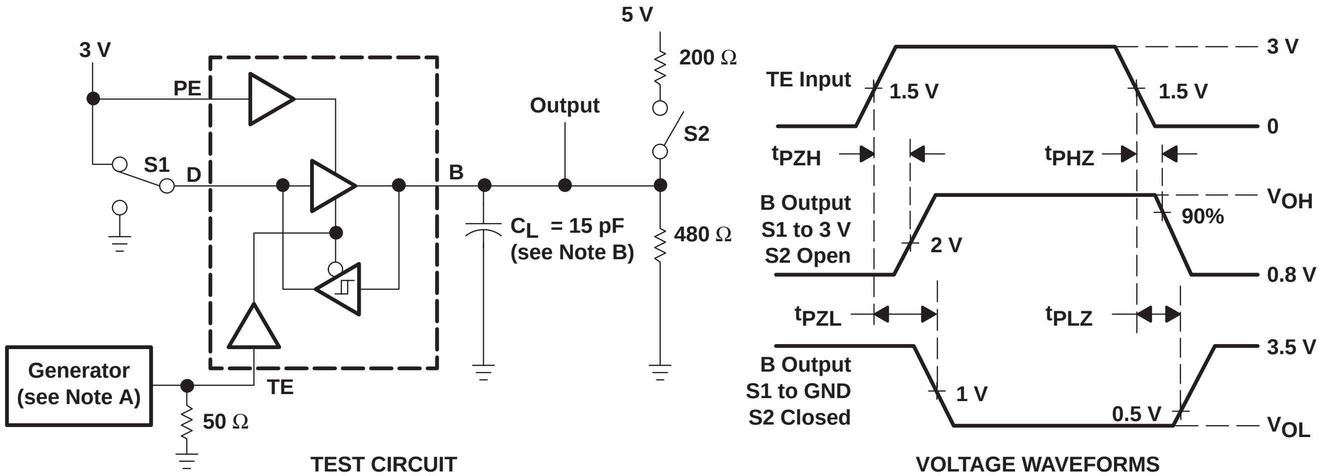
Figure 1. Terminal-to-Bus Test Circuit and Voltage Waveforms



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

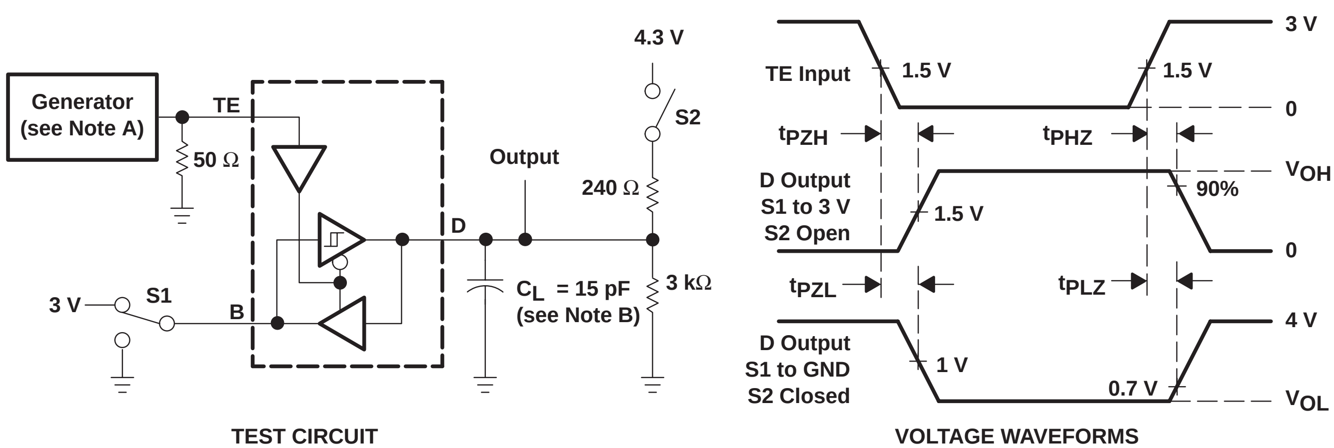
Figure 2. Bus-to-Terminal Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50\ \Omega$.
B. C_L includes probe and jig capacitance.

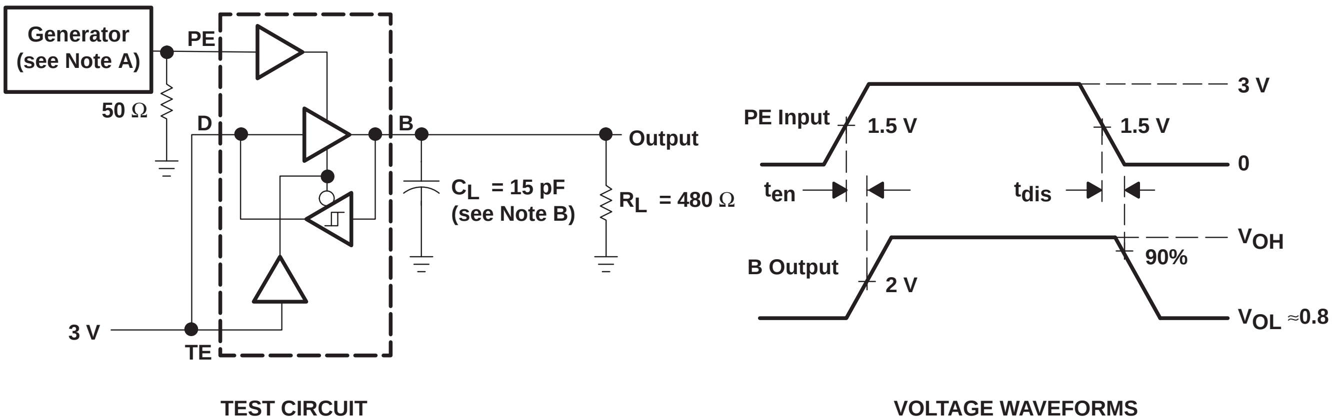
Figure 3. TE-to-Bus Test Circuit and Voltage Waveforms



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50\ \Omega$.
B. C_L includes probe and jig capacitance.

Figure 4. TE-to-Terminal Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.

B. C_L includes probe and jig capacitance.

Figure 5. PE-to-Bus Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

TERMINAL HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

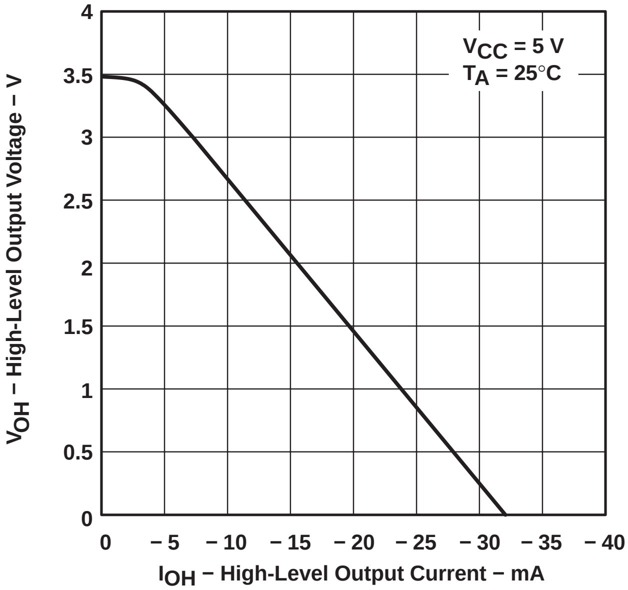


Figure 6

TERMINAL LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

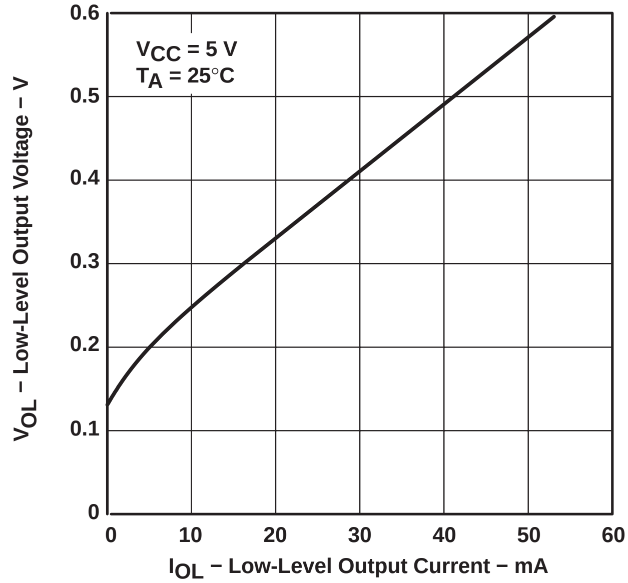


Figure 7

TERMINAL OUTPUT VOLTAGE
vs
BUS INPUT VOLTAGE

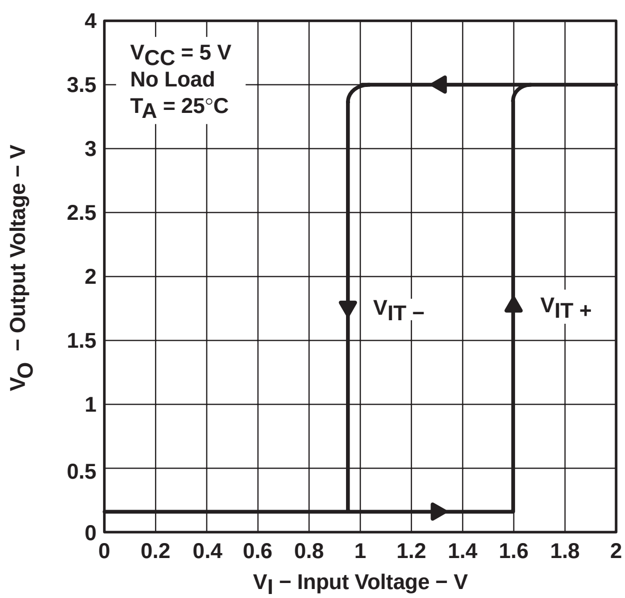


Figure 8

TYPICAL CHARACTERISTICS

BUS HIGH-LEVEL OUTPUT VOLTAGE vs BUS HIGH-LEVEL OUTPUT CURRENT

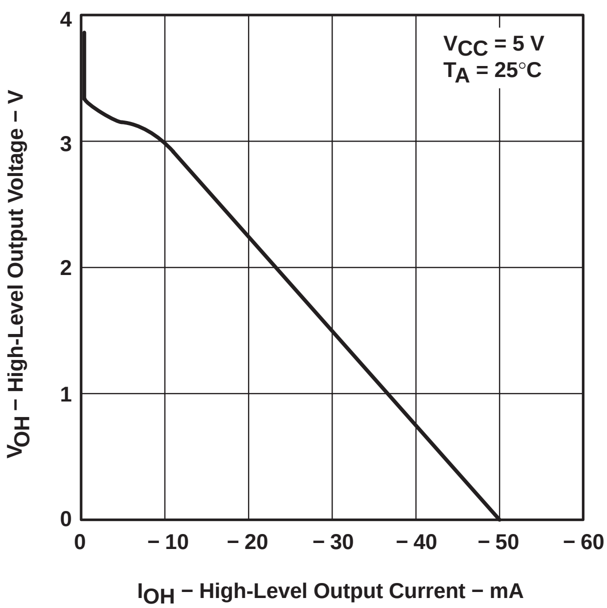


Figure 9

BUS LOW-LEVEL OUTPUT VOLTAGE vs BUS LOW-LEVEL OUTPUT CURRENT

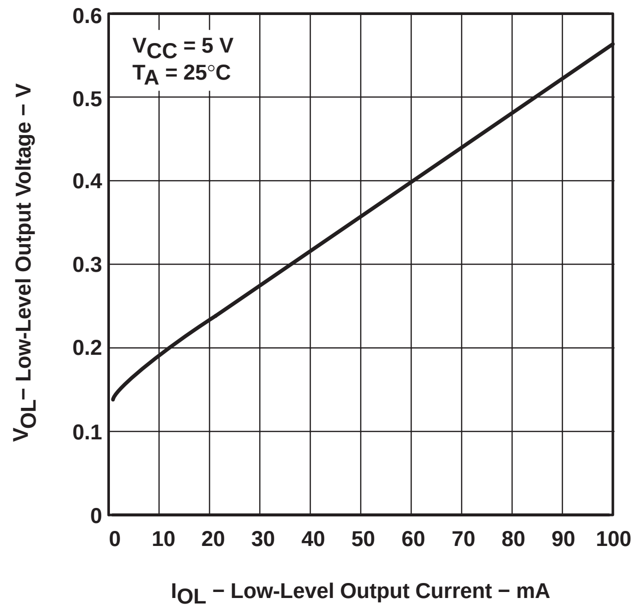


Figure 10

BUS OUTPUT VOLTAGE vs TERMINAL INPUT VOLTAGE

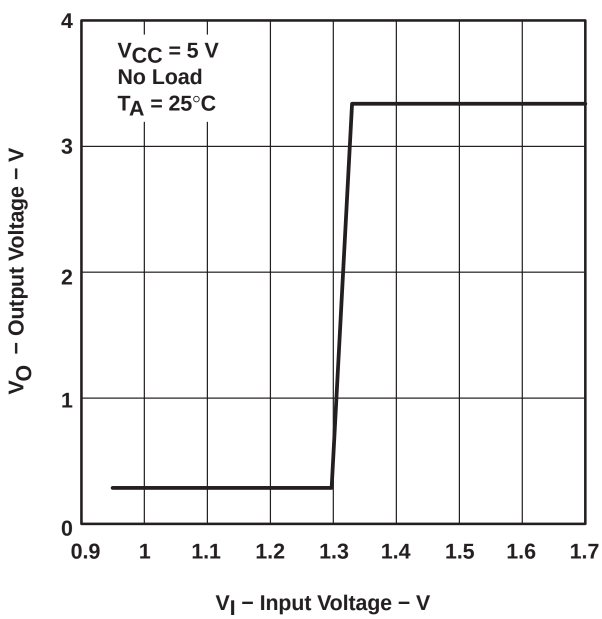


Figure 11

BUS CURRENT vs BUS VOLTAGE

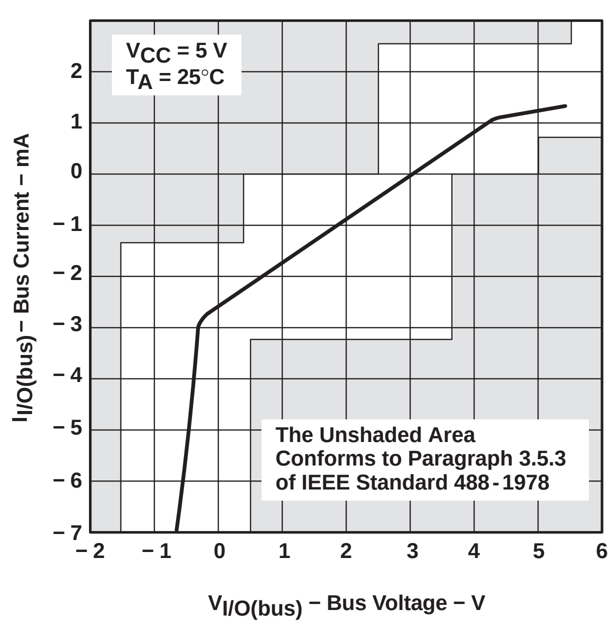


Figure 12

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/ Ball Finish	MSL Peak Temp [3]	Samples (Requires Login)
SN75ALS160DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75ALS160DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75ALS160DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75ALS160DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75ALS160DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75ALS160DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN75ALS160N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN75ALS160NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN75ALS160 :

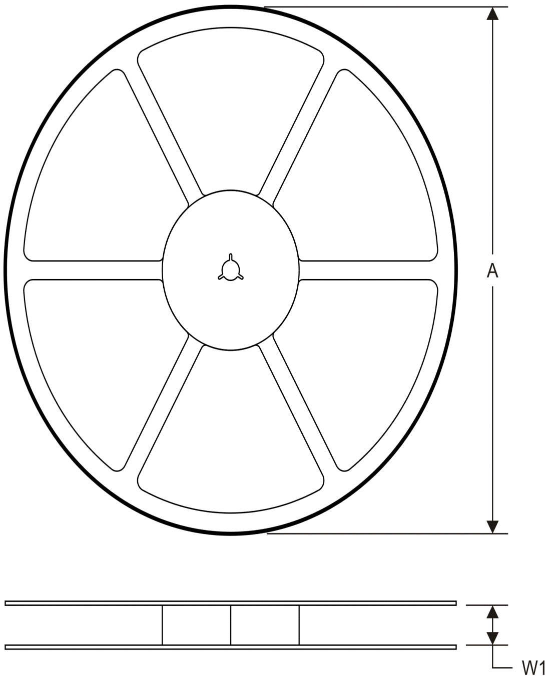
- Military: SN55ALS160

NOTE: Qualified Version Definitions:

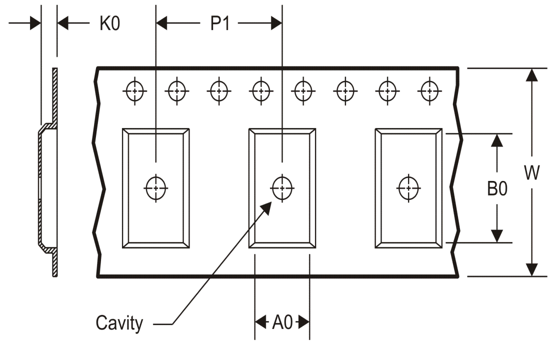
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



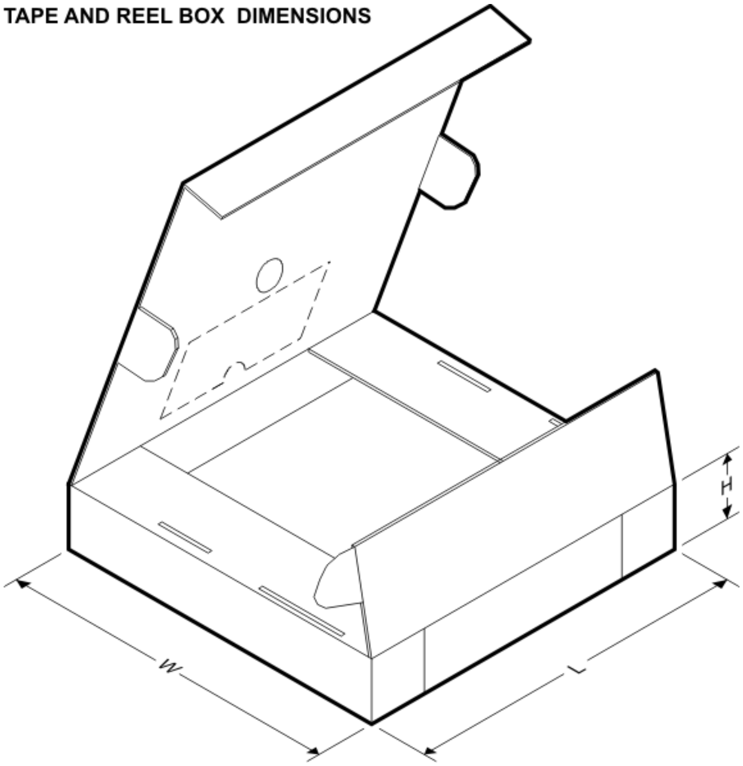
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS160DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN75ALS160DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

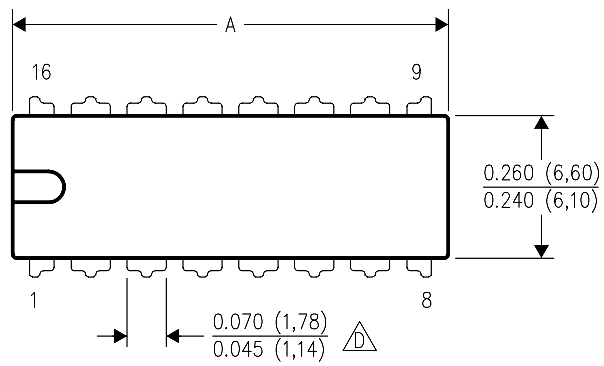


*All dimensions are nominal

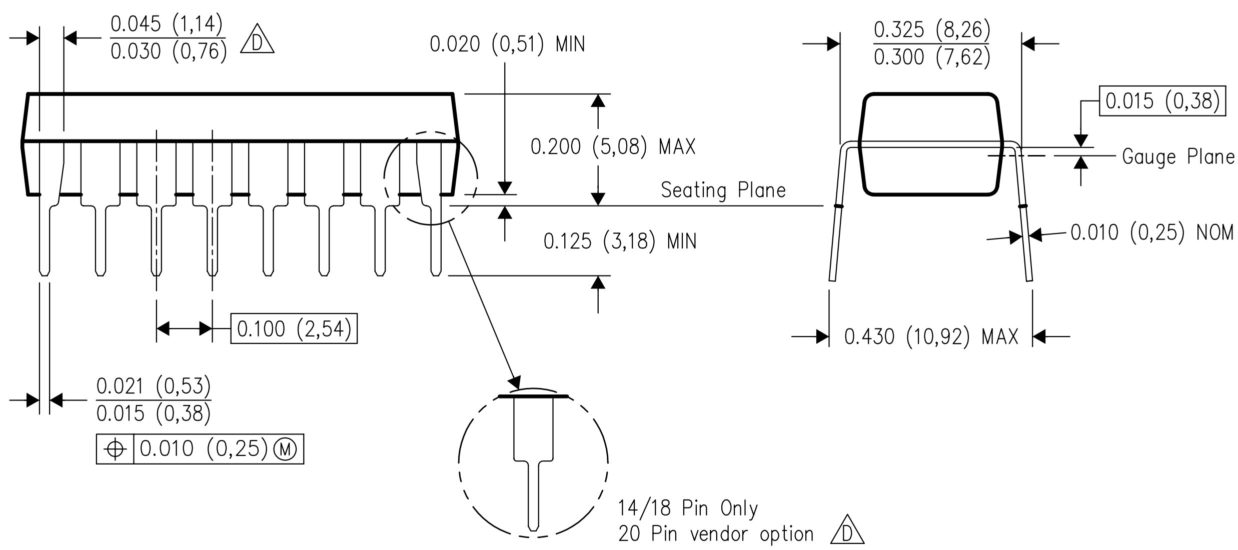
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS160DWR	SOIC	DW	20	2000	600.0	144.0	84.0
SN75ALS160DWR	SOIC	DW	20	2000	367.0	367.0	45.0

N (R–PDIP–T**) PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



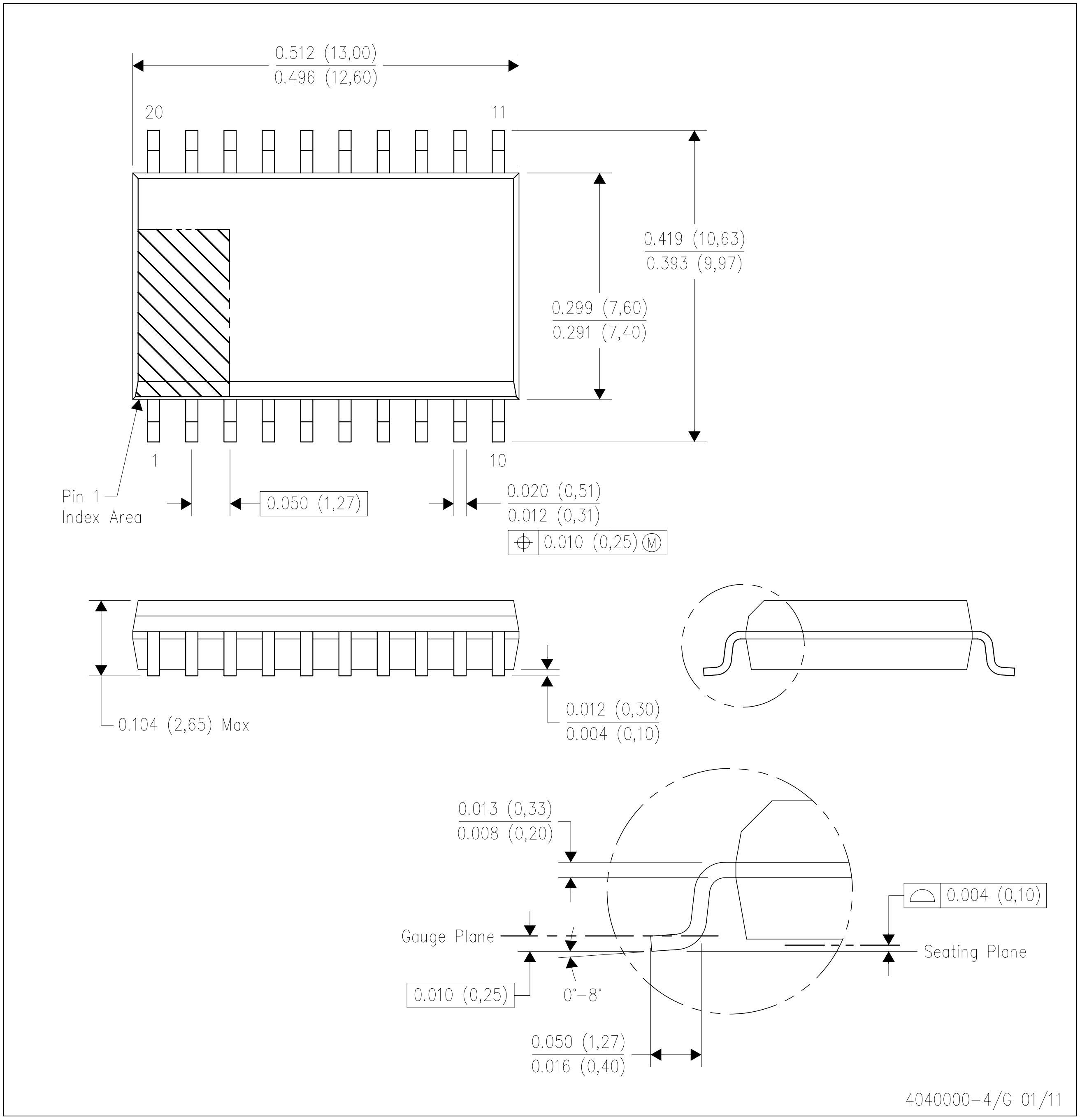
PINS ** / DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

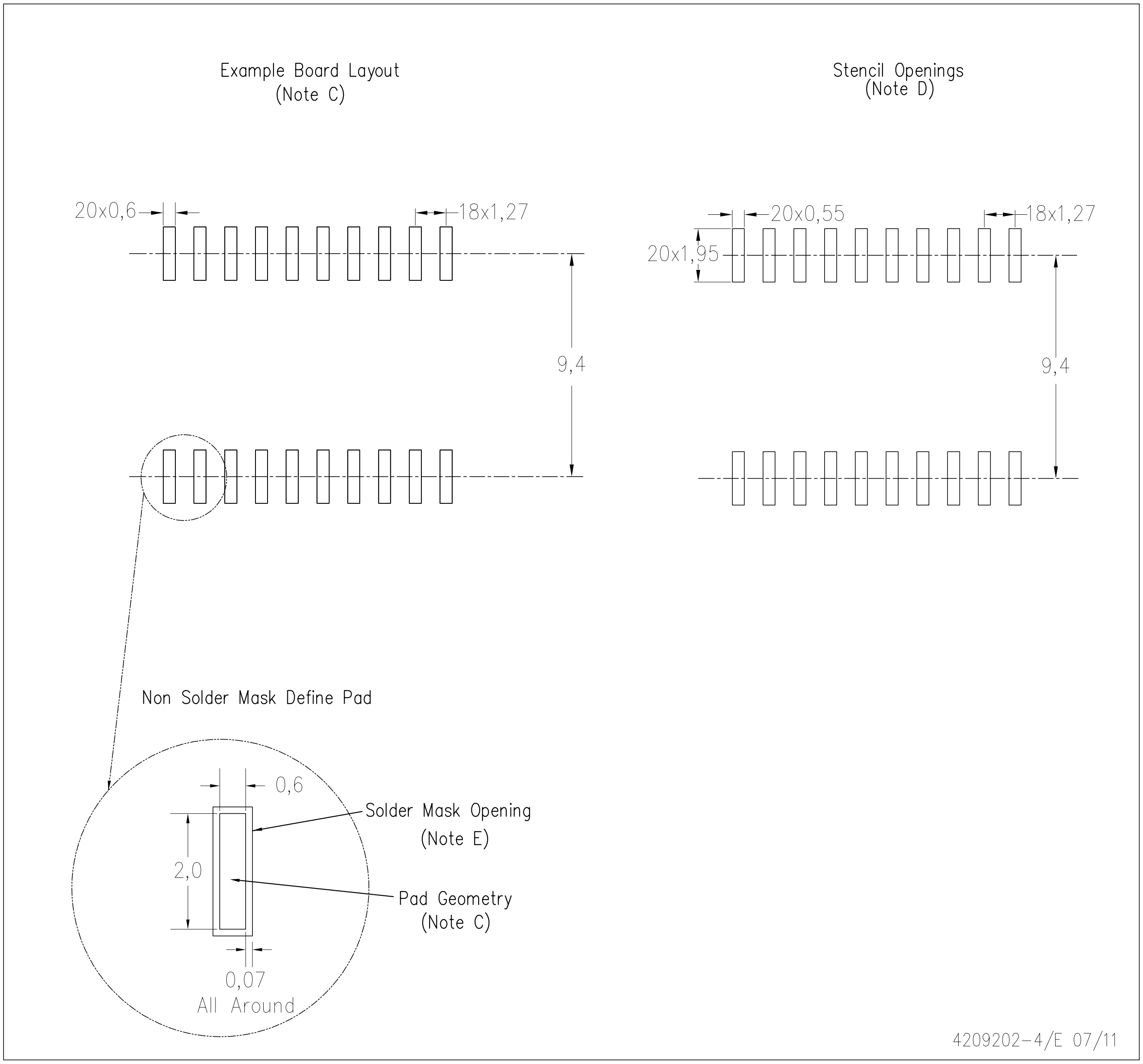
NOTES:
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
- D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R–PDSO–G20) PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AC.

DW (R–PDSO–G20) PLASTIC SMALL OUTLINE



NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

IMPORTANT NOTICE

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